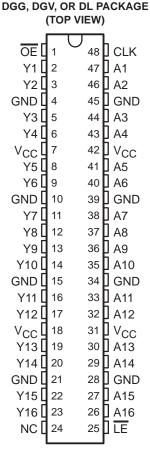
- **Member of the Texas Instruments** Widebus™ Family
- **EPIC** ™ (Enhanced-Performance Implanted **CMOS) Submicron Process**
- Ideal for Use in PC100 Register DIMM
- **Designed to Comply With JEDEC 168-Pin** and 200-Pin SDRAM Buffered DIMM Specification
- **ESD Protection Exceeds 2000 V Per** MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 250 mA Per **JESD 17**
- **Package Options Include Plastic Shrink** Small-Outline (DL), Thin Shrink Small-Outline (DGG), and Thin Very Small-Outline (DGV) Packages

description

This 16-bit universal bus driver is designed for 1.65-V to 3.6-V V_{CC} operation.

Data flow from A to Y is controlled by the output-enable (\overline{OE}) input. The device operates in the transparent mode when the latch-enable (LE) input is low. When \overline{LE} is high, the A data is latched if the clock (CLK) input is held at a high or low logic level. If LE is high, the A data is stored in the latch/flip-flop on the low-to-high transition of CLK. When \overline{OE} is high, the outputs are in the high-impedance state.



NC - No internal connection

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN74ALVC16334 is characterized for operation from -40°C to 85°C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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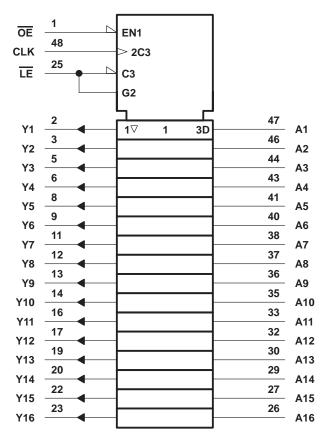


FUNCTION TABLE

	INF	OUTPUT		
OE	LE	CLK	Α	Y
Н	Χ	Х	Χ	Z
L	L	Χ	L	L
L	L	X	Н	Н
L	Н	\uparrow	L	L
L	Н	\uparrow	Н	Н
L	Н	L or H	Χ	Y ₀ †

[†] Output level before the indicated steady-state input conditions were established

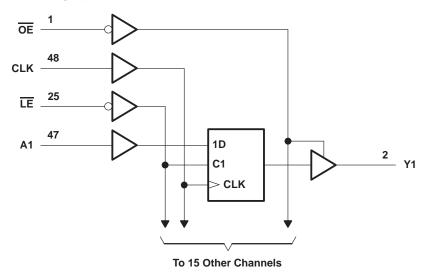
logic symbol‡



[‡]This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.



logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}		
Input voltage range, V _I (see Note 1)		
Output voltage range, VO (see Notes 1 and 2)		
Input clamp current, I_{IK} ($V_I < 0$)		
Output clamp current, I _{OK} (V _O < 0)		–50 mA
Continuous output current, IO		±50 mA
Continuous current through each V _{CC} or GND		±100 mA
Package thermal impedance, θ _{JA} (see Note 3):	DGG package	89°C/W
	DGV package	93°C/W
	DL package	94°C/W
Storage temperature range, T _{stg}		–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

- 2. This value is limited to 4.6 V maximum.
- 3. The package thermal impedance is calculated in accordance with JESD 51.



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recommended operating conditions (see Note 4)

			MIN	MAX	UNIT
VCC	Supply voltage		1.65	3.6	V
		$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$	0.65 × V _{CC}		
\vee_{IH}	High-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	1.7		V
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	2	3.6 //CC //CC //CC //CC //CC //CC //CC //	
	Low-level input voltage Input voltage Output voltage	$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$		$0.35 \times V_{CC}$	
V_{IL}	Low-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		0.7	V
	Input voltage	$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$		0.8	
VI	Input voltage		0	Vcc	V
٧o	Output voltage		0	Vcc	V
		V _{CC} = 1.65 V		-4	
la	/IL Low-level input voltage /I Input voltage /O Output voltage OH High-level output current OL Low-level output current	V _{CC} = 2.3 V		-12	mA
ЮН		V _{CC} = 2.7 V			-12
		V _{CC} = 3 V		.65 3.6 × V _{CC} 1.7 2 0.35 × V _{CC} 0.7 0.8 0 V _{CC} -4 -12 -12 -24 4 12 12 24 10	
		V _{CC} = 1.65 V		4	
1	Lour lovel output ourrent	V _{CC} = 2.3 V		12	A
IOL	Low-level output current	V _{CC} = 2.7 V		12	mA
		V _{CC} = 3 V		24	
Δt/Δν	Input transition rise or fall rate			10	ns/V
TA	Operating free-air temperature		-40	85	°C

NOTE 4: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

P/	ARAMETER	TEST CC	ONDITIONS	VCC	MIN	TYP [†]	MAX	UNIT	
		I _{OH} = -100 μA		1.65 V to 3.6 V	V _{CC} -0.	2			
		$I_{OH} = -4 \text{ mA}$		1.65 V	1.2				
		I _{OH} = -6 mA		2.3 V	2				
Voн		I _{OH} = -100 μA	V						
		I _{OH} = -12 mA		2.7 V	2.2				
	VOH		3 V	2.4					
VoL	I _{OH} = -24 mA	3 V	2						
		I _{OL} = 100 μA	1.65 V to 3.6 V			0.2			
Vol		I _{OL} = 4 mA	1.65 V			0.45	v		
		I _{OL} = 6 mA	2.3 V			0.4			
VOL		lo. – 12 mΛ		2.3 V			0.7	v	
		IOF = 15 MM		2.7 V			0.4		
		I _{OL} = 24 mA		3 V			0.55		
Ц		$V_I = V_{CC}$ or GND		3.6 V			±5	μΑ	
loz		$V_O = V_{CC}$ or GND		3.6 V			±10	μΑ	
Icc		$V_I = V_{CC}$ or GND,	IO = 0	3.6 V			40	μΑ	
Δlcc	·	One input at V _{CC} – 0.6 V,	Other inputs at V _{CC} or GND	3 V to 3.6 V			750	μΑ	
C.	Control inputs	VI - Vac or CND	5		5			n.E	
Ci	Data inputs	AL = ACC OF QUAD		3.3 V	5.5			pF	
Со	Outputs	VO = VCC or GND		3.3 V		7.5		pF	

[†] All typical values are at $V_{CC} = 3.3 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figures 1 through 3)

				V _{CC} =	1.8 V	V _{CC} =	2.5 V 2 V	V _{CC} =	2.7 V	V _{CC} =		UNIT
				MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
fclock	f _{clock} Clock frequency			‡		150		150		150	MHz	
	tw Pulse duration	LE low		‡		3.3		3.3		3.3		ns
t _W	Puise duration	CLK high or low		‡		3.3		3.3		3.3		115
	t_{SU} Setup time Data before $\overline{LE}\uparrow$	Data before CLK↑		‡		1.4		1.7		1.5		
t _{su}		CLK high	‡		1.2		1.6		1.3		ns	
		Data before LE	CLK low	‡		1.4		1.5		1.2		
	t _h Hold time	Data after CLK↑	•	‡		0.9		0.9		0.9		
th		Data after LE ↑	CLK high or low	‡		1.1		1.1		1.1		ns

[‡] This information was not available at the time of publication.



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switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figures 1 through 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	VCC =	1.8 V	V _{CC} =	2.5 V 2 V	VCC =	2.7 V	V _{CC} =	3.3 V 3 V	UNIT
	(IIVFOT)	(OUTFUT)	MIN	TYP	MIN	MAX	MIN	MAX	MIN	MAX	
f _{max}			†		150		150		150		MHz
^t pd	Α			†	1	3.7		3.6	1.1	3.3	
	LE	Y		†	1	4.8		5	1.3	4.4	ns
	CLK			†	1	4.4		4.5	1	4.1	
t _{en}	ŌĒ	Y		†	1	5.4		5.4	1.1	4.6	ns
^t dis	ŌĒ	Y		†	1	4.1		4.5	1.7	4.4	ns

[†] This information was not available at the time of publication.

switching characteristics from 0° C to 65° C, $C_{L} = 50$ pF

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = ± 0.1	UNIT	
	(1141 01)	(0011 01)	MIN	MAX	
	А	Υ	1.2	3.2	ns
^t pd	CLK	Y	1.1	4	ns

operating characteristics, $T_A = 25^{\circ}C$

PARAMETER			TEST CONDITIONS	V _{CC} = 1.8 V	V _{CC} = 2.5 V	V _{CC} = 3.3 V	UNIT		
TAKAWETEK		TEST CONDITIONS	TYP	TYP	TYP	OIALL			
Power dissipation				C		Ť	31	36	nE.
C _{pd}	capacitance	Outputs disabled	$C_L = 0$, $f = 10 \text{ MHz}$	†	7	11	pF		

[†] This information was not available at the time of publication.



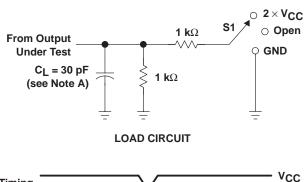
VCC

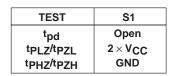
0 V

V_{CC}/2

PARAMETER MEASUREMENT INFORMATION $V_{CC} = 1.8 \text{ V}$

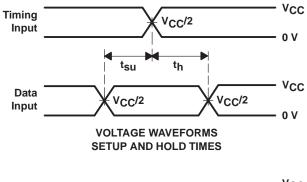
Input

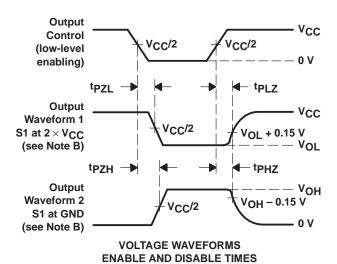


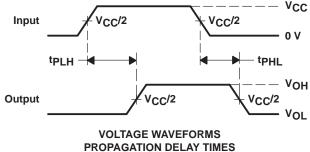


V_{CC}/2

VOLTAGE WAVEFORMS PULSE DURATION





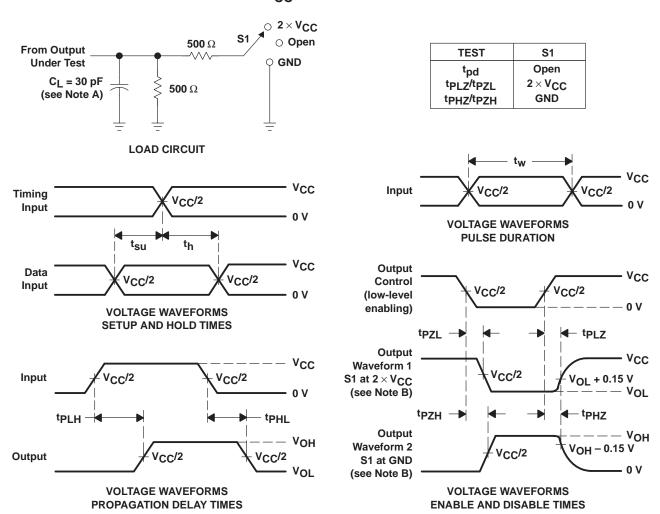


NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50~\Omega$, $t_f \leq$ 2 ns, $t_f \leq$ 2 ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpl 7 and tpH7 are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tpLH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION $V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$



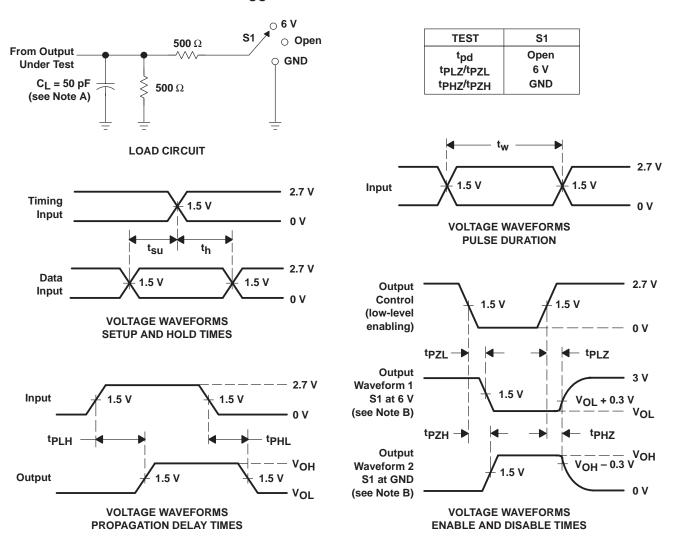
NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_Q = 50 \Omega$, $t_f \leq 2$ ns. $t_f \leq 2$ ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpLz and tpHz are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tpLH and tpHL are the same as tpd.

Figure 2. Load Circuit and Voltage Waveforms



PARAMETER MEASUREMENT INFORMATION $V_{CC} = 2.7 \text{ V}$ AND 3.3 V \pm 0.3 V



- NOTES: A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_{O} = 50 \,\Omega$, $t_{r} \leq 2.5 \,\text{ns}$, $t_{f} \leq 2.5 \,\text{ns}$.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. tpzL and tpzH are the same as ten.
 - G. tpLH and tpHL are the same as tpd.

Figure 3. Load Circuit and Voltage Waveforms

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